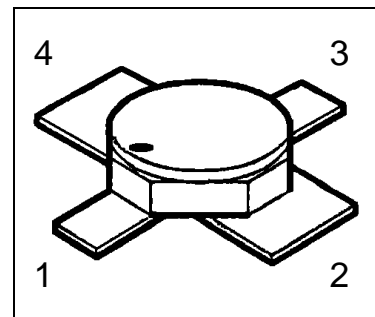


HiRel NPN Silicon RF Transistor


BFY420(ES)

Features

- For Low Current Applications
- For Oscillators up to 10 GHz
- Noise Figure $F = 1.1$ dB at 1.8 GHz
Outstanding $G_{ms} = 21$ dB at 1.8 GHz
- Hermetically sealed microwave package
- Transition Frequency $f_T = 22$ GHz
- **SIEGET[®] 25-Line**
Infineon Technologies Grounded Emitter Transistor-
25 GHz f_T -Line



Product validation

-  **ESA Space Qualified**
ESCC Detail Spec. No.: 5611/008
Type Variant No. 02

Description

ESD: Electrostatic discharge sensitive device,
observe handling precautions!

Table 1 Product information

Type	Comment	Pin Configuration				Package
		1	2	3	4	
BFY420(ES)	For flight use	C	E	B	E	Micro-X
BFY420(P) ¹	Not for flight use ¹					

¹ (P) parts have the same fit, form and function as (ES) parts,
no screening acc. to Chart F3 in ESCC Generic Specification No. 5010

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Maximum ratings

1 Maximum ratings

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Collector-emitter voltage	V_{CE0}	-	-	4.5	V	
Collector-base voltage	V_{CBO}	-	-	15	V	
Emitter-base voltage	V_{EBO}	-	-	1.5	V	
Collector current	I_C	-	-	35	mA	
Base current	I_B	-	-	3	mA	
Total power dissipation ¹	P_{tot}	-	-	160	mW	$T_S \leq 129\text{ }^\circ\text{C}$
Junction temperature	T_j	-	-	175	$^\circ\text{C}$	
Operating temperature	T_{op}	-65	-	175	$^\circ\text{C}$	
Storage temperature	T_{stg}	-65	-	175	$^\circ\text{C}$	

¹ For $T_S > 129\text{ }^\circ\text{C}$ derating is required. T_S is measured on the collector lead at the soldering point to the PCB

Thermal characteristics

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction –soldering point	$R_{th,JS}$	-	-	285	K/W	T_s is measured on the collector lead at the soldering point to the PCB
Soldering Temperature	T_{sol}	-	-	250	°C	Duration 5 seconds maximum at a distance of not less than 0.5mm from the device body and the same lead shall not be resoldered until 3 minutes have elapsed.

Electrical characteristics

3 Electrical characteristics

at $T_A=25^\circ\text{C}$, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Collector-base cutoff current	I_{CBO}	-	-	30	nA	$V_{CB} = 5\text{V}, I_E = 0\text{A}$
Collector-emitter cutoff current ¹	I_{CEX}	-	-	200	μA	$V_{CE} = 4.5\text{V}, I_B = 1\mu\text{A}$
Emitter base cutoff current	I_{EBO}	-	-	20	μA	$V_{EB} = 1.5\text{V}, I_C = 0\text{A}$
DC current gain	h_{FE}	50	90	150	-	$I_C = 5\text{mA}, V_{CE} = 1\text{V}$

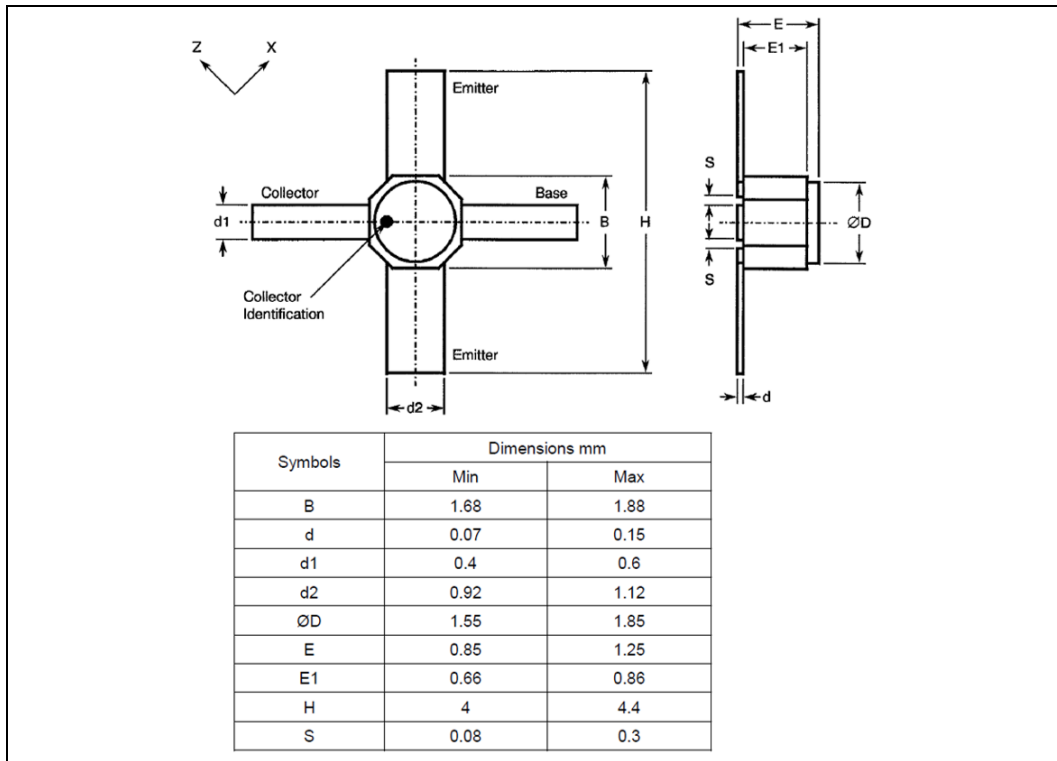
Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Transition frequency	f_T	20	22	-	GHz	$I_C = 30\text{mA}, V_{CE} = 3\text{V}, f = 2\text{GHz}$
Collector-base capacitance	C_{CB}	-	0.14	0.9	pF	$V_{CB} = 2\text{V}, V_{BE} = v_{be} = 0, f = 1\text{MHz}$
Collector-emitter capacitance	C_{CE}	-	0.46	0.85	pF	$V_{CE} = 2\text{V}, V_{BE} = v_{be} = 0, f = 1\text{MHz}$
Emitter-base capacitance	C_{EB}	-	0.67	3	pF	$V_{EB} = 0.5\text{V}, V_{CB} = v_{cb} = 0, f = 1\text{MHz}$
Noise Figure	F	-	1.1	1.7	dB	$I_C = 5\text{mA}, V_{CE} = 2\text{V}, f = 1.8\text{GHz}, Z_S = Z_{\text{Sopt}}$
Insertion power gain	$ S_{21e} ^2$	14	18	-	dB	$I_C = 20\text{mA}, V_{CE} = 2\text{V}, f = 1.8\text{GHz}, Z_S = Z_L = 50\Omega$
Power Gain ²	G_{ms}	-	21	-	dB	$I_C = 20\text{mA}, V_{CE} = 2\text{V}, f = 1.8\text{GHz}, Z_S = Z_{\text{Sopt}}, Z_L = Z_{\text{Lopt}}$
1dB Compression point	$P_{-1\text{dB}}$	-	12	-	dBm	$I_C = 20\text{mA}, V_{CE} = 2\text{V}, f = 1.8\text{GHz}, Z_S = Z_{\text{Sopt}}, Z_L = Z_{\text{Lopt}}$

¹ This test assures $V_{(BR)CE0} > 4.5\text{V}$

$$^2 G_{ms} = \left| \frac{S_{21}}{S_{12}} \right|$$

4 Package outlines



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Email: erratum@infineon.com

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